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(54) **WIRING SUBSTRATE AND METHOD FOR
MANUFACTURING THE SAME**

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ABSTRACT

A wiring substrate includes an insulating layer including inorganic particles and resin, a seed layer formed on a surface of the insulating layer, and a conductor layer including a conductor pattern and formed on the seed layer. The surface of the insulating layer is a roughened surface formed such that the roughened surface of the insulating layer has exposed portions of the inorganic particles and resin with gaps at interfaces where the inorganic particles and the resin are in contact, and the seed layer is formed on the roughened surface of the insulating layer such that the seed layer is formed along the exposed portions of the inorganic particles and resin exposed on the roughened surface of the insulating layer and is not formed in the gaps at the interfaces where the inorganic particles and the resin are in contact.

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